

ABSTRACT

A method and apparatus for preparing a perforated panel for reticulation to a film adhesive. The method includes supporting the perforated panel. The method also includes adhering the film adhesive to the perforated panel without initiating a cure of the film adhesive. The method applies a vacuum to the film adhesive. Next the method will move the perforated panel at a predetermined speed through a reticulation unit. Next the method will soften the film adhesive and finally remove the film adhesive from the perforations by an airflow. The method is generally used for creating acoustic sheet panels for use in many industries.